ISO 16413:2020 (E)

Evaluation of thickness, density and interface width of thin films by X-ray reflectometry — Instrumental requirements, alignment and positioning, data collection, data analysis and reporting

Contents

Foreword

Introduction

1 Scope

2 Normative references

3 Terms and definitions

3.1 Terms and definitions
3.2 Symbols and abbreviated terms

4 Instrumental requirements, alignment and positioning guidelines

4.1 Instrumental requirements for the scanning method
4.1.1 Schematic diagrams
4.1.2 Incident beam — Requirements and recommendations
4.1.2.1 Incident beam — Requirements
4.1.2.2 Incident beam — Recommendations
4.1.3 Specimen — Requirements and recommendations
4.1.3.1 Specimen — Requirements
4.1.3.2 Specimen — Recommendations
4.1.4 Goniometer — Requirements
4.1.5 Detector — Requirements
4.2 Instrument alignment
4.3 Specimen alignment

5 Data collection and storage

5.1 Preliminary remarks
5.2 Data scan parameters
5.3 Dynamic range
5.4 Step size (peak definition)
5.4.1 Fixed intervals scan
5.4.2 Continuous scan
5.5 Collection time (accumulated counts)
5.6 Segmented data collection
5.7 Reduction of noise
5.8 Detectors
5.9 Environment
5.10 Data storage
5.10.1 Data output format
5.10.2 Headers

6 Data analysis

6.1 Preliminary data treatment
6.2 Specimen modelling
6.2.1 General
6.2.2 Interface width models
6.3 Simulation of XRR data
6.4 General examples
6.5 Data fitting

7 Information required when reporting XRR analysis

7.1 General
7.2 Experimental details
7.3 Analysis (simulation and fitting) procedures
7.4 Methods for reporting XRR curves
7.4.1 Independent and dependent variables
7.4.2 Graphical plotting of XRR data

Annex A (informative) Example of report for an oxynitrided silicon wafer

Page count: 32